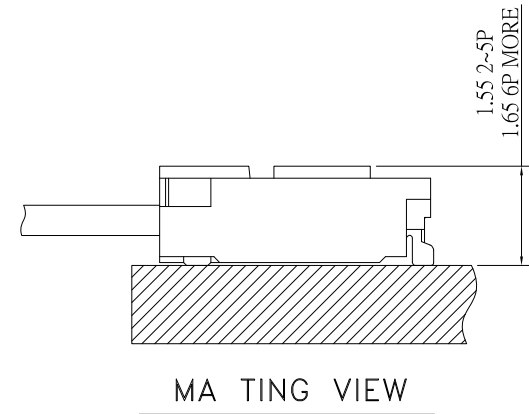
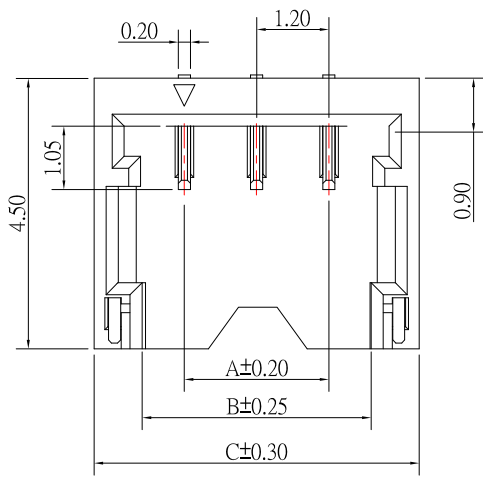
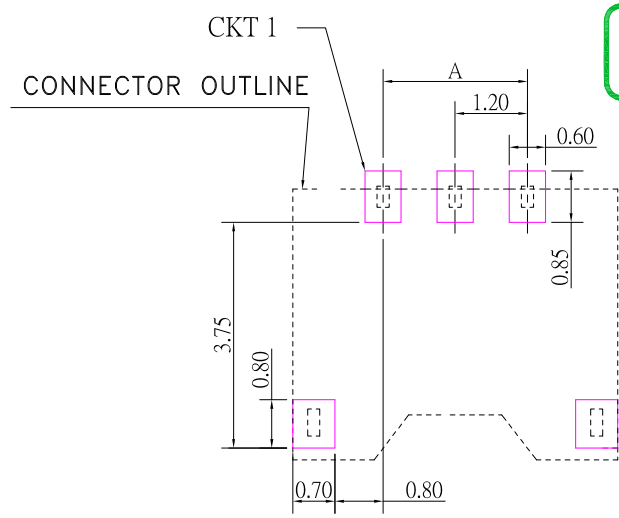


Poles	Dimensions(mm)		
	A	B	C
02	1.20	2.60	4.20
03	2.40	3.80	5.40



P.C.B LAYOUT MOUNTING PATTERN

- 1.Material
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Solder Tabs: Brass
- 2.Plating
 - 2.1 Contact: Gold Plated.
 - 2.2 Solder Tabs: Tin plated.
- 3.Rating:
 - 3.1 Voltage Rating: 50V AC / DC
 - 3.2 Current Rating: 2.0A AC / DC
 - 3.3 Contact Resistance: 20mΩ max.
 - 3.4 Temperature Range: -25°C~+85°C.
 - 3.5 Dielectric Withstanding Voltage: 500V AC / 1min.
 - 3.6 Insulation Resistance: 100MΩ min.

8	更新圖面	Jack	080923
7	新增不同PIN數側面圖	Jack	072922
6	更新圖面	Jack	102821
5	更新Temperature Range	Jack	102920
4	新增P.C.B LAYOUT尺寸	Jack	061020
3	更新樣式	Jack	022520
2	更新為AO版	Jack	042916
1	新增pin選項	Jack	041416
ITEM NO.	DESCRIPTION	DRAWN	DATE

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR
Jack Lu	08/09/23	FINISH		MODLE	WAFER 1.2mm 嵌入式 Wire To Board
CHECKED BY:	DATE	SCALE	1 : 1	DWG NO.	WF-1201RSxx-S304
Jacky Chen	08/09/23	SHEET NO.	1 of 1	PART NO.	WF-1201RSxx-S304
APPROVED BY:	DATE				
Tony Kao	08/09/23				